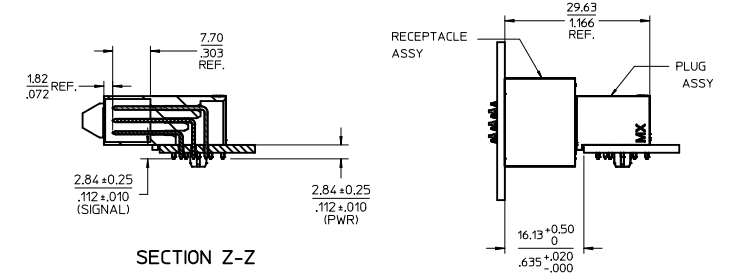
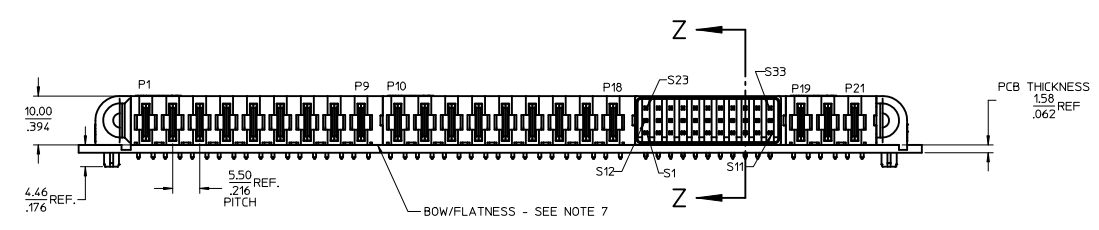


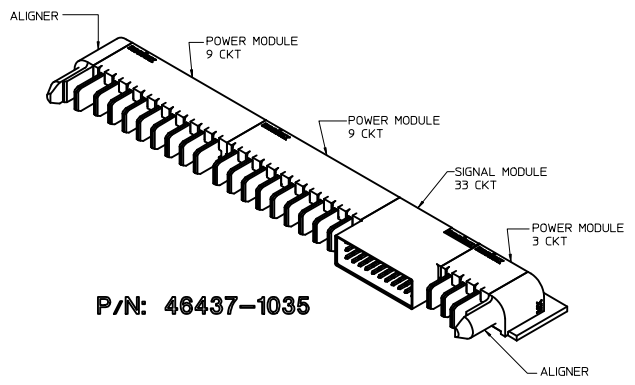
RECOMMENDED PCB LAYOUT AND KEEP-OUT ZONE



SECTION Z-Z

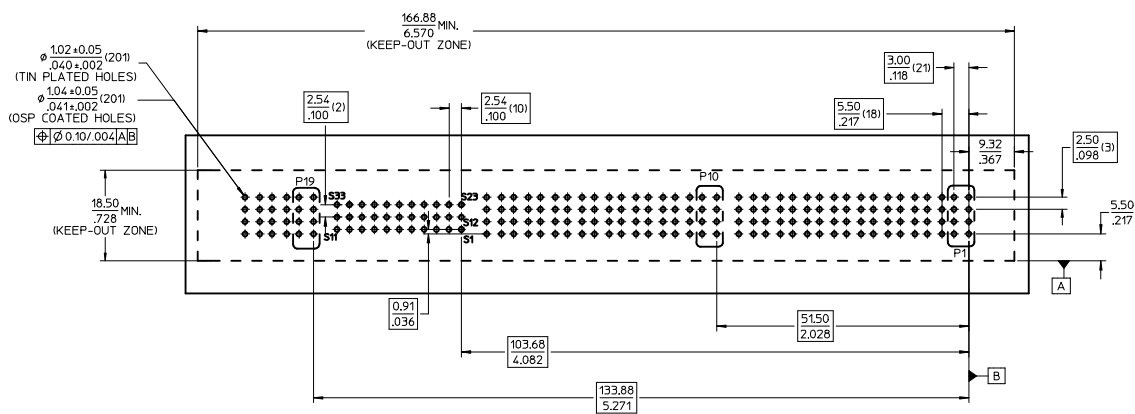
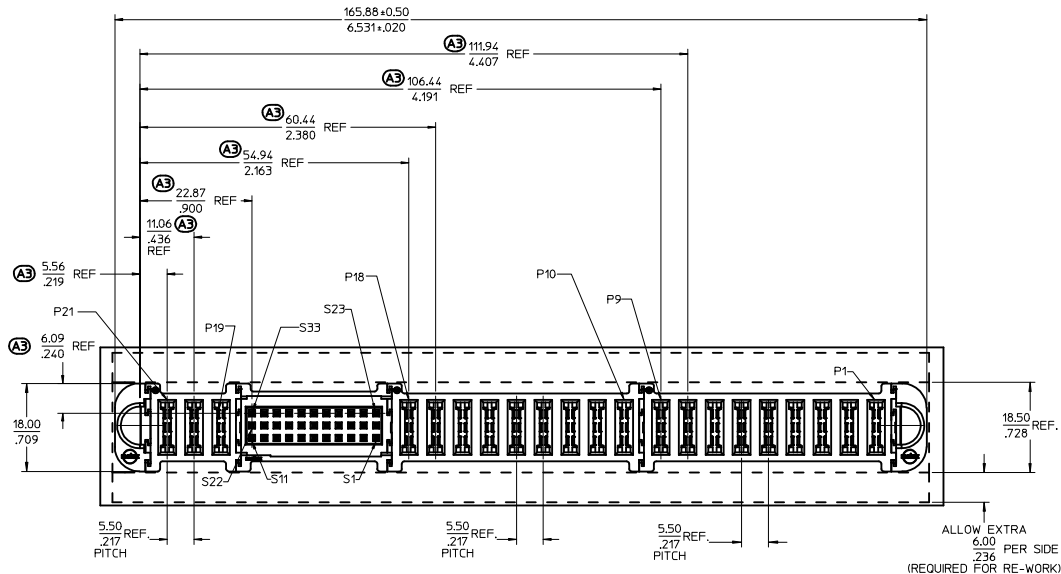
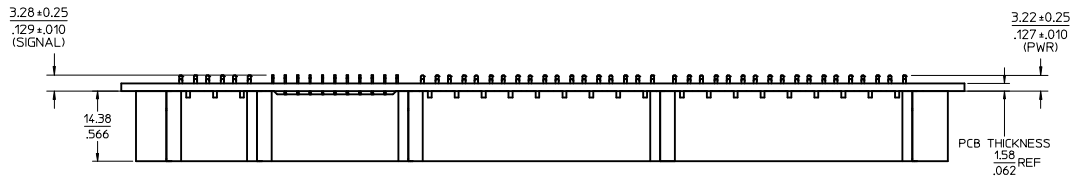
NOTES:

- MATERIAL:
  - HOUSINGS: HIGH TEMPERATURE PLASTIC (LCP OR EQUIVALENT)
  - TERMINALS: HIGH CONDUCTIVITY COPPER ALLOY
  - PLATING: .00127/.000050 NICKEL OVERALL WITH 0.00254/.000100 SELECTIVE TIN ON SOLDER TAILS AND 0.000762/.000030 SELECTIVE GOLD ON CONTACT AREA.
- PACKAGING: ASSEMBLIES TO BE TRAY PACKED PER PACKAGING SPEC PK-46437-XXX.
- INDIVIDUAL MODULES ARE RATED FOR VARIOUS VOLTAGE AND CURRENT RATINGS PER PS-46436-100.
- PC BOARD REQUIRES SOLDER THRU HOLES. REFER TO PS-46436-100 FOR DETAILS.
- PRODUCT TO MEET ROHS REQUIREMENTS.
- ASSEMBLY MATES TO MOLEX VERTICAL RECEPTACLE ASSEMBLY P/N: 46562-1035.
- BOW/FLATNESS - 0.12MM/25MM MAX.

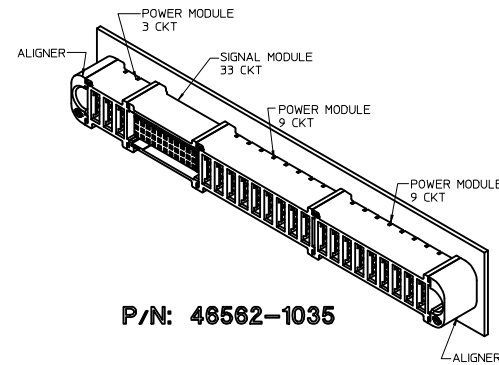


P/N: 46437-1035

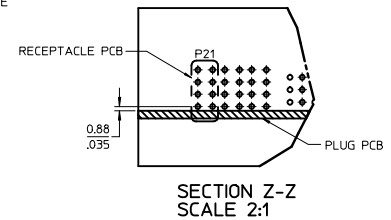
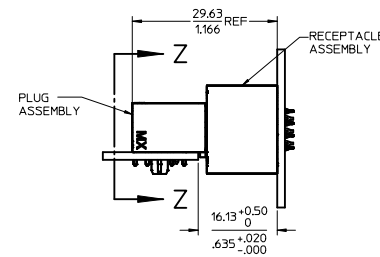
ADD NOTES EC NO. UCP2011-3951 DRAWN/DATE 2011/06/14 CHYK/DATE 2011/06/14 APPR/PATEL 2011/08/31	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		mm INCH	MM/IN	2:1	METRIC	☉	
		4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE			
		3 PLACES ± --- ± .010	CHKD BY DATE	IBM PLUG ASSY			
	2 PLACES ± 0.25 ± .010	APPROVED BY DATE	TEN60 POWER FAMILY				
	1 PLACE ± 0.25 ± ---	PATEL 2008/05/15	3DC-33S-9DC-9DC				
	ANGULAR ± 1/2°		MOLEX INCORPORATED				
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. 46437-1035	DOCUMENT NO. SD-46437-135		SHEET NO. 1 OF 1		
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



RECOMMENDED PCB LAYOUT AND KEEP-OUT ZONE



P/N: 46562-1035



NOTES:

1. MATERIAL:
  - HOUSINGS: HIGH TEMPERATURE PLASTIC, BLACK, UL 94V-0 (LCP OR EQUIVALENT)
  - TERMINALS: HIGH CONDUCTIVITY COPPER ALLOY.
  - PLATING: 0.00127/.000050 NICKEL OVERALL WITH 0.00254/.000100 SELECTIVE TIN ON COMPLIANT PINS. AND 0.000762/.000030 SELECTIVE GOLD ON CONTACT AREA.
2. PACKAGING ASSEMBLIES TO BE TRAY PACKED PER PACKAGING SPEC PK-46562-001.
3. INDIVIDUAL MODULES ARE RATED FOR VARIOUS VOLTAGE AND CURRENT RATINGS PER PS-46436-100.
4. PC BOARD REQUIRES SOLDER THRU HOLES, SEE PS-46436-100 FOR DETAILS.
5. PRODUCT TO MEET RoHS REQUIREMENTS.
6. ASSEMBLY MATES WITH PLUG ASSEMBLY, P/N 46437-1035.

ADD DIMENSIONS IEC NO: UCF2010-0421 DRAWN: JUILLES 2009/09/15 CHYK: 2009/09/16 APPR: APATEL 2009/09/23 REV:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM/IN	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	DRAWN BY DATE MKARADI MAS 2008/05/12	TITLE	RECEPTACLE ASSY TEN60 POWER FAMILY 3DC-33S-9DC-9DC		
		3 PLACES ± --- ± .010	CHECKED BY DATE KOSTIC 2008/05/15	MOLEX INCORPORATED MATERIAL NO. 46562-1035 DOCUMENT NO. SD-46562-135			
		2 PLACES ± 0.25 ± .010	APPROVED BY DATE PATEL 2008/05/15	SHEET NO. 1 OF 1			
	1 PLACE ± 0.25 ± ---	ANGULAR ± 1/2°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				